ON Semiconductor

Update Notification

Document # : FPCN16200X1
Issue Date: 2 October 2015

Title of Change:	Phase 2 Copper Wire for VHVIC Products in SOIC and TSSOP packages in Carmona, Philippines
Proposed first ship date:	21 December 2015
Contact information:	Contact your local ON Semiconductor Sales Office or <Scott.Brow@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <Scott.Brow@onsemi.com>
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Ken.Fergus@onsemi.com>.
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other _______________

Change Sub-Category(s):

☐ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☒ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ________________________

Sites Affected:

☐ All site(s)
☐ not applicable
☒ ON Semiconductor site(s) :
ON Carmona, Philippines
☐ External Foundry/Subcon site(s)

Description and Purpose:

The devices listed in this FPCN were released to production after FPCN16200 was released to customers and prior to the factory conversion to Cu wire which will occur on 9/28/15. In order to give customers adequate time to evaluate the products listed in this Update Notification, these products will not convert to Cu wire until 12/21/15. A reliability summary supporting this change can be found in FPCN16200 and can be provided upon request.

List of affected Standard Parts:

NCP1240AD065R2G
NCP1240BD065R2G
NCP1240BD100R2G
NCP1240FD065R2G
NCP1248AD065R2G
NCP1248AD100R2G
NCP1236ED100R2G
NCP1252DDR2G

List of affected Customer Specific Parts:

SCY99194AD065R2G